

PATENT ASSIGNMENT

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SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1"><thead><tr><th>Name</th><th>Execution Date</th></tr></thead><tbody><tr><td>Chun Hsiung TSAI</td><td>12/12/2011</td></tr><tr><td>Tsan-Chun WANG</td><td>12/12/2011</td></tr><tr><td>Su-Hao LIU</td><td>12/12/2011</td></tr><tr><td>Tsz-Mei KWOK</td><td>12/12/2011</td></tr><tr><td>Chii-Ming WU</td><td>12/12/2011</td></tr></tbody></table>	Name	Execution Date	Chun Hsiung TSAI	12/12/2011	Tsan-Chun WANG	12/12/2011	Su-Hao LIU	12/12/2011	Tsz-Mei KWOK	12/12/2011	Chii-Ming WU	12/12/2011	
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RECEIVING PARTY DATA													
Name:	TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD.												
Street Address:	No. 8, Li-Hsin Rd. VI, Hsinchu Science Park												
City:	Hsinchu												
State/Country:	TAIWAN												
Postal Code:	300												
PROPERTY NUMBERS Total: 1													
<table border="1"><thead><tr><th>Property Type</th><th>Number</th></tr></thead><tbody><tr><td>Application Number:</td><td>13324331</td></tr></tbody></table>	Property Type	Number	Application Number:	13324331									
Property Type	Number												
Application Number:	13324331												
CORRESPONDENCE DATA													
Fax Number:	(703)518-5499												
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ATTORNEY DOCKET NUMBER:	T5057-639												
NAME OF SUBMITTER:	Randy A. Noranbrock												
Total Attachments: 1 source=efiledassgn#page1.tif													

OP \$40.00 13324331

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PATENT
REEL: 027375 FRAME: 0089

ASSIGNMENT

In consideration of the premises and other good and valuable consideration in hand paid, the receipt and sufficiency of which is hereby acknowledged, the undersigned,

- | | |
|---------------------|-----------------|
| 1) Chun Hsiung TSAI | 4) Tsz-Mei KWOK |
| 2) Tsan-Chun WANG | 5) Chii-Ming WU |
| 3) Su-Hao LIU | |

who has made a certain new and useful invention, hereby sells, assigns and transfers unto

TAIWAN SEMICONDUCTOR MANUFACTURING COMPANY, LTD. having a place of business at **No. 8, Li-Hsin Rd. VI, Hsinchu Science Park, Hsinchu 300, Taiwan (R.O.C.)**

its successors and assigns (hereinafter designated "ASSIGNEE") the entire right, title and interest for the United States of America as defined in 35 U.S.C. 100 in the invention entitled

MECHANISMS FOR FORMING STRESSOR REGIONS IN A SEMICONDUCTOR DEVICE

(a) for which an application for United States Letters Patent was filed on 2011-12-13, and identified by United States Patent Application No. 13/324,331; or

(b) for which an application for United States Letters Patent was executed on _____,

and the undersigned hereby authorizes and requests the United States Commissioner of Patents and Trademarks to issue any and all United States Letters Patent which may be granted therefore and any and all extensions, divisions, reissues, continuations, or continuations-in-part thereof, and the right to all benefits under the International Convention for the Protection of Industrial Property to the said ASSIGNEE, for its interest as ASSIGNEE, its successors, assigns and legal representatives; the undersigned agrees that the attorneys of record in said application shall hereafter act on behalf of said ASSIGNEE;

AND the undersigned hereby agrees to transfer a like interest, and to render all necessary assistance in making application for and obtaining original, divisional, reissued or extended Letters Patent of the United States, upon request of the said ASSIGNEE, its successors, assigns and legal representatives, and without further remuneration, in and to any improvements, and applications for patent based thereon, growing out of or related to the said invention; and to execute any papers by the said ASSIGNEE, its successors, assigns and legal representatives, deemed essential to ASSIGNEE's full protection and title in and to the invention hereby transferred.

SIGNED on the date indicated aside my signature:

1) ✓ Chun Hsiung Tsai
Name: Chun Hsiung TSAI

✓ 2011.12.12
Date:

2) ✓ Tsan-Chun Wang
Name: Tsan-Chun WANG

✓ 2011.12.12
Date:

3) ✓ Su-Hao LIU
Name: Su-Hao LIU

✓ 2011.12.12
Date:

4) ✓ Tsz-Mei kwok
Name: Tsz-Mei KWOK

✓ 2011.12.12
Date:

5) ✓ Chii-Ming Wu
Name: Chii-Ming WU

✓ 2011.12.12
Date: